

Asia Pacific Circuits is a leader in the manufacture of technologically advanced PCBs, backplane and sub-system assemblies. We offer One-stop solution for Electronics Manufacturing Services EMS. Including PCB fabrication, sourcing of components, and complete electronic PCB assembly. With a state of the art facility and modern technology, we cater to customers in a broad spectrum of industries. Time to market, and represents how the company's time-critical, one-stop manufacturing services enable customers to shorten the time required to develop new products and bring them to market.

Headquarters	Shenzhen
Founded	1998
Ownership	Private
Employees	Approximately 1,500
Total Facilities	Over 0.3 million square feet
Divisions	(1) Focused PCB Assembly / (2) PCB Fabrication
Manufacturing Locations	No. 55A, Bao'an Ave, Shenzhen, China
Sales Locations	Asia & North America

Focused on
Turnkey PCB Assembly
PCB Boards • Components • PCB Assembly
www.apc-pcbassembly.com

Contact Information

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Custom Assembly

Asia Pacific Circuits Operations

August 2014

Backplanes

Dimensions up to 28" x 52"	Press-fit (compliant-pin)	AOI & X-ray inspection
Thickness up to .400"	Surface mount (chip, QFP, BGA)	Level 2, 3 & 4 testing
Custom & Industry Standard	Wave / Selective solder	Conformal coating

Flex & Rigid-Flex

Dimensions up to 22" x 52"	Press-fit (compliant-pin)	AOI & X-ray inspection
Passive & active components	Surface mount (chip, QFP, BGA)	Level 2, 3 & 4 testing

RF / Microwave

Dimensions up to 22" x 34"	1-piece hermetic GPO & GPPO	X-ray inspection
Blind via, surface mount, thru-hole		RF testing (20+ GHz)

Integrated Assembly

Card cage through cabinet	Power supplies / Fan trays	Functional testing
Backplanes / Midplanes	Peripherals & controllers	Mil / Aero conduction cooled
Harnessing / Cabling	I/O interfaces	

Conventional PCBs

Up to 56 layers	Over 50 UL approved laminates	Heavy Copper up to 5 oz.
Dimensions up to 23" x 42.5"	Embedded passives	Thin core dielectrics
Thickness up to .325"	Mixed dielectrics	

HDI

Stacked Microvias / Via in pad / Via on hole / FCV	UL Recognized	Copper & epoxy hole fill
0.4 mm pitch BGA		

Flex & Rigid-Flex

Type 2, 3 & 4 flex (double sided, multilayer & rigid-flex)	Acrylic, epoxy & adhesive-less polyimide flex materials	Bikini cut, loose leaf construction
Up to 16 R-Flex layers	Thickness up to .118"	Combination surface finishes
Epoxy fillet		

IC Substrate

2, 4, 6 layers (2+2+2 stacked via)	Type: SIP, CSP, BOC	Thin board: 130um(2L), 220um(4L)
BT material	Fine trace width / Space 30/30um	Flip chip C4 pad
Wire bonding (ENEPIG, Soft gold, Hard gold)	Via in pad / Via on hole / FCV	

Thermal Management

Passive & active designs	Epoxy & B-stage films	Copper base materials
Buried metal core constructions	Thermal & conductive bonding	Various surface finishes
In-house bonding		

Approvals & Qualifications

ISO 9000 (Quality System)	UL Recognized	TL 9000 (Telecom)
ISO 14001 (Environmental)	IPC-A-600, Class 3	AS9100 (Aerospace)
RoHS compliant		TS16949 (Automotive)

Engineering & Design Services

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PCBs (Rigid, Flex, Rigid-Flex & Backplanes)

PCB Cost / Benefit Analysis	PCB Schematic & Simulation	PCB CAD Layout & Mfg Doc
- Panelization	- OrCAD	- Allegro
- Stackup / Construction	- DX Designer	- BoardStation
- Laminate Optimization	- TAS PCB	- Expedition
- Valor DFM Check	- HSPICE & HFSS	- PADS

Backplanes Assemblies

Via & Trace Modeling	Connector Specification Advice	Signal Integrity Characterization
Single-Ended Critical Net Simulation	Connector Pin-Out Advice	Design Rules Optimization
Differential Channel Simulation	Via Counter-Boring / Backdrilling	Design for Assembly Advice
Cross-Talk Management	Power Voltage Drop Analysis	Design for Testability Advice
Impedance Control & Optimization	Power Thermal Gradient Analysis	Schematics & CAD Layout

Integrated Systems (Card Cages, Chassis & Enclosures)

Power Input & Conditioning	Enclosure Thermal Management	Structural Integrity Simulation
Power Distribution & Control	Convection Cooling & Air Movers	Enclosure / Card Rack CAD
PICMG Stds Customization	Conduction Cooling & Heat Sinks	Pro / Engineer
Industry Stds Confidence Testing	Acoustical Noise Management	SolidWorks
Industrial Design Assistance	Fan Speed Controls	AutoCAD